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Yasuhiro YAMAMOTO, Hajime OGAWA, Taketo HEISHI and Shohei MICHIMOTO	Name: <u>Matsushita Electric Industrial Co., Ltd.</u>
Additional name(s) of conveying party(ies) attached? No	Street Address: 1006, Oaza Kadoma, Kadoma-shi,
Nature of conveyance:	Osaka 571-8501, Japan
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4. Application number(s) or patent number(s):	77
If this document is being filed together with a new application, the A. Patent Application No.(s) NEW, filed September 28, 2004	B. Patent No.(s)
Additional numbers	
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1
Name: <u>WENDEROTH, LIND & PONACK, L.L.P.</u> Attn: Michael S. Huppert , Esq.	7. Total fee (37 CFR 3.41) \$ <u>40.00</u> X Enclosed (Check No. 64362)
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ASSIGNMENT

	In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned Yasuhiro YAMAMOTO, Hajime OGAWA, Taketo HEISHI and Shohei MICHIMOTO
insert Name(s) of Inventor(s)	
	the undersigned hereby sell(s) and assign(s) to
Insert Name(s) of Assignee(s)	Matsushita Electric Industrial Co., Ltd.
Address	of 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, Japan
	(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as
Títle of Invention	COMPILER APPARATUS AND LINKER APPARATUS
Date of Signing of Application	for which an application for patent in the United States has been executed by the undersigned
or Application	on February 10, 2004
	The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, D.C. 20006-1021, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

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name(s).	d by the undersigned on the date(s) opposite the undersigned	i
Date August 24, 2004	, Name of the Inventor <u>Yasuhiro Yamamoto</u>	_
Date August sit, 2004	, Name of the Inventor Hajime Ogawa	
Date August 24, 2004	, Name of the Inventor Taketo Keishi	
Date August 34, 3004	, Name of the Inventor Michimoto Shopei	
	, Name of the Inventor	
Date	, Name of the Inventor	
Date	, Name of the Inventor	
Date	, Name of the Inventor	_
Date	, Name of the Inventor	
Date	, Name of the Inventor	
This	day of,, before me me personally known as the individual(s) who executed the nowledge to me that he (they) executed the same of his (their) et forth.) owr
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	Official Title	,
The above application may	be more particularly identified as follows:	
U.S. Application Serial No.	Filing Date	_
Applicant Reference Number	Atty Docket No.	_
Title of Invention		

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